

**FIG. 1 B**

FIG. 2A

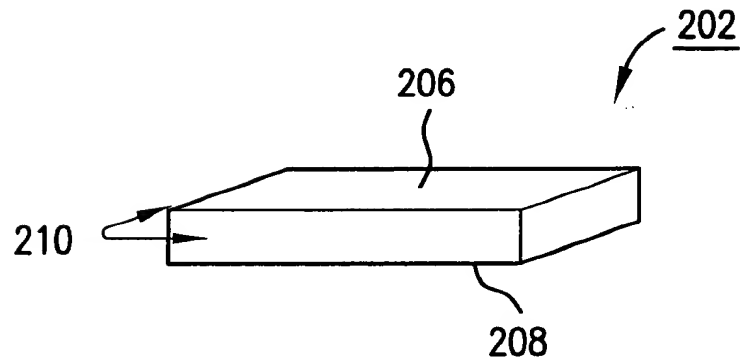


FIG. 2B

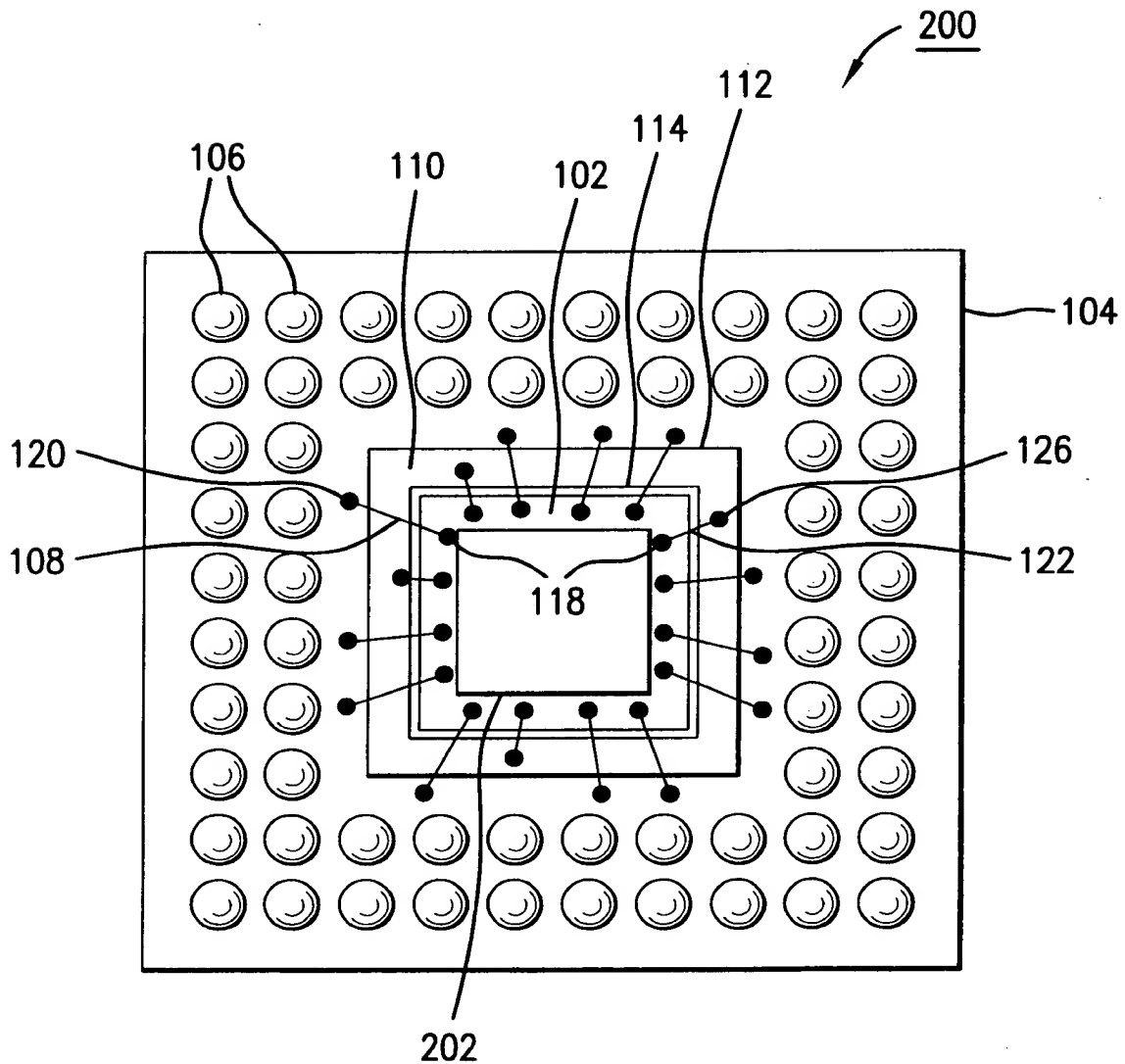


FIG. 2C

**FIG. 3A**

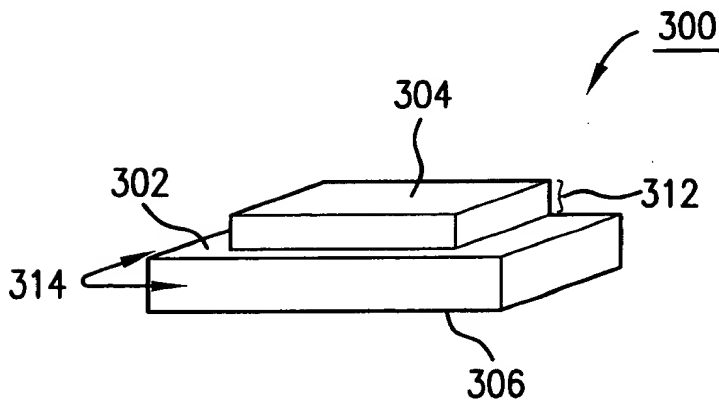


FIG. 3B

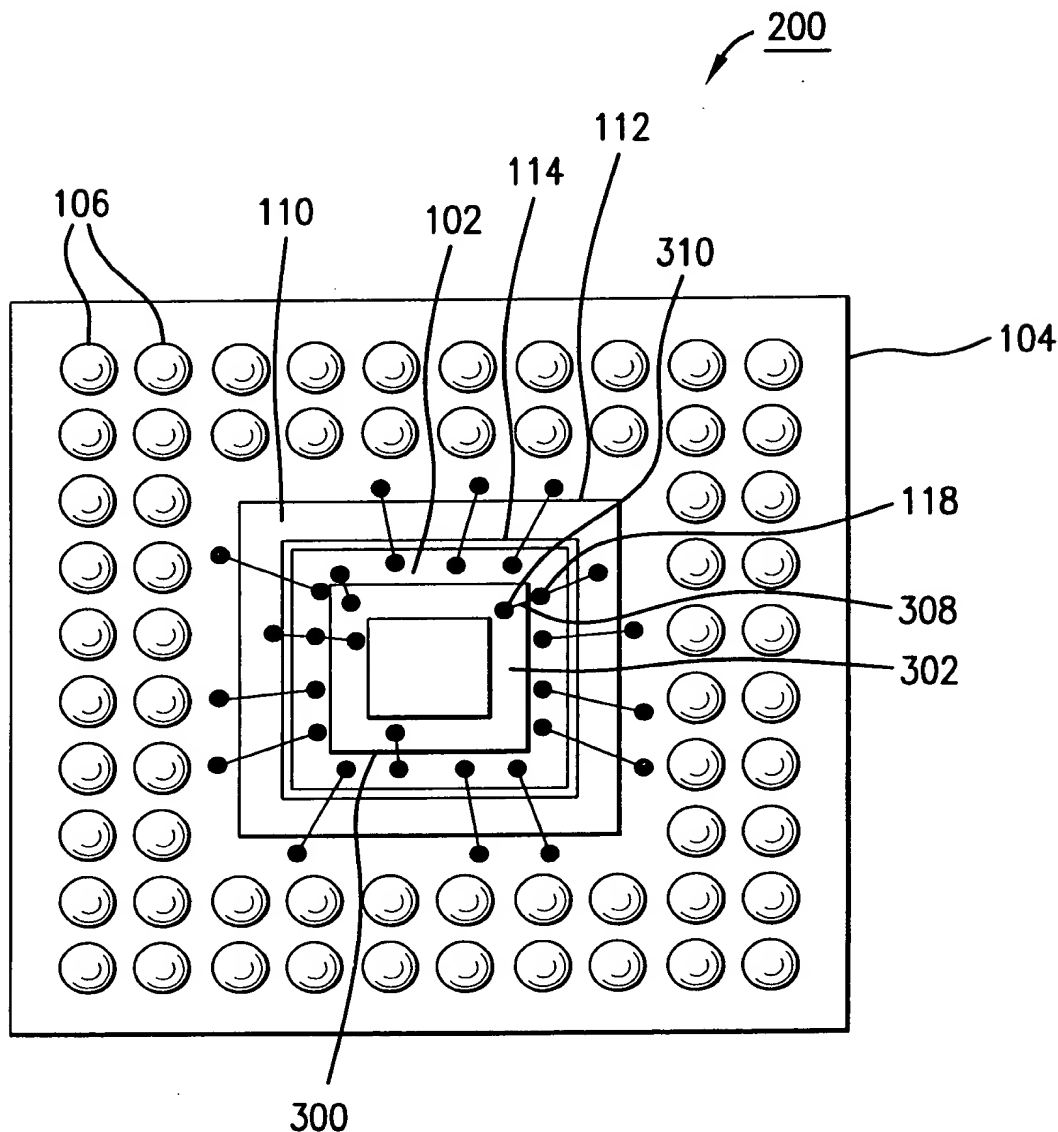
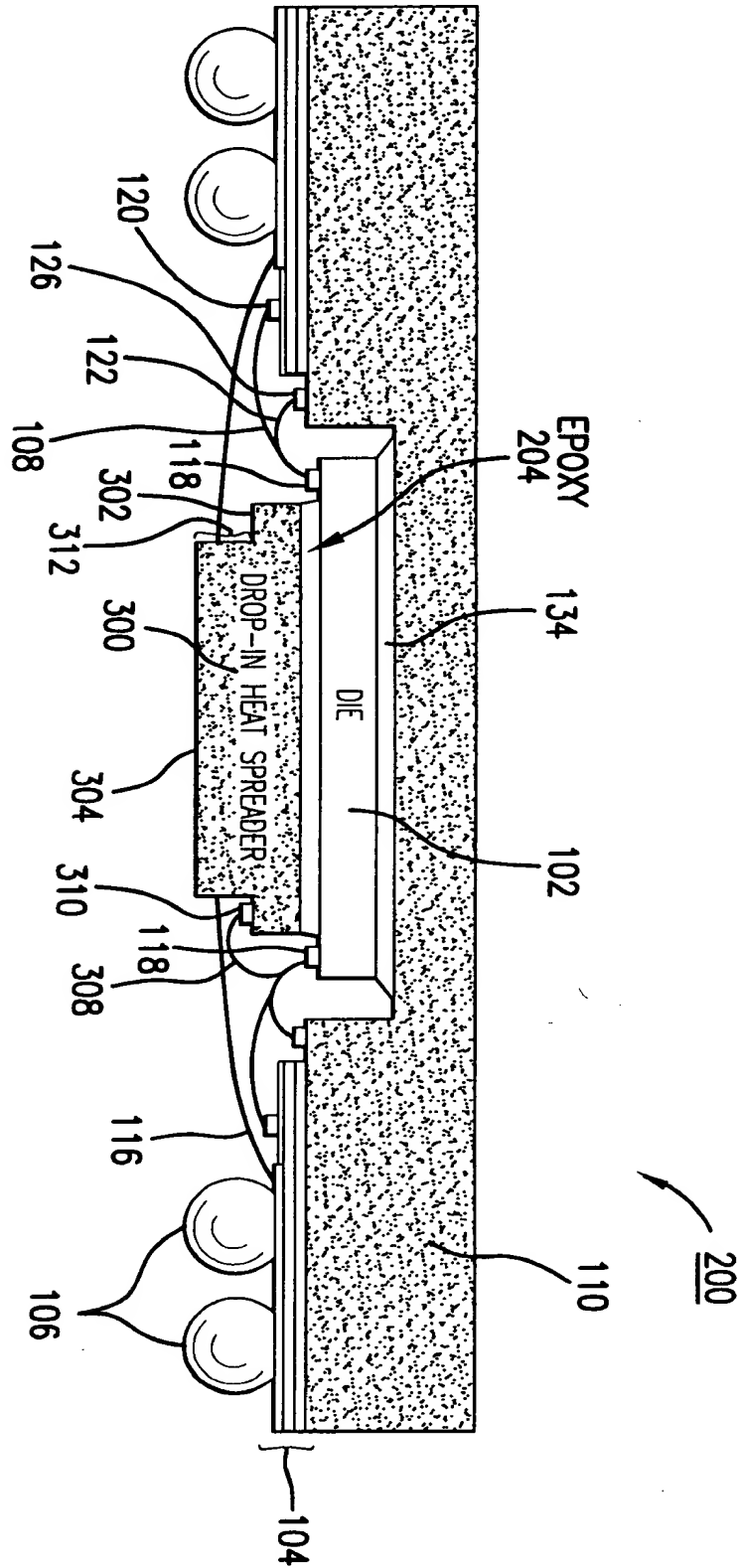


FIG. 3C



FIG. 3D





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Int. No. 1875.0210000; Group Art Unit: 2826  
inventor(s): Khan *et al.* ; Tel: 202/371-2600  
title: Die-Down Ball Grid Array Package With Die-Attached  
Heat Spreader and Method For Making the Same

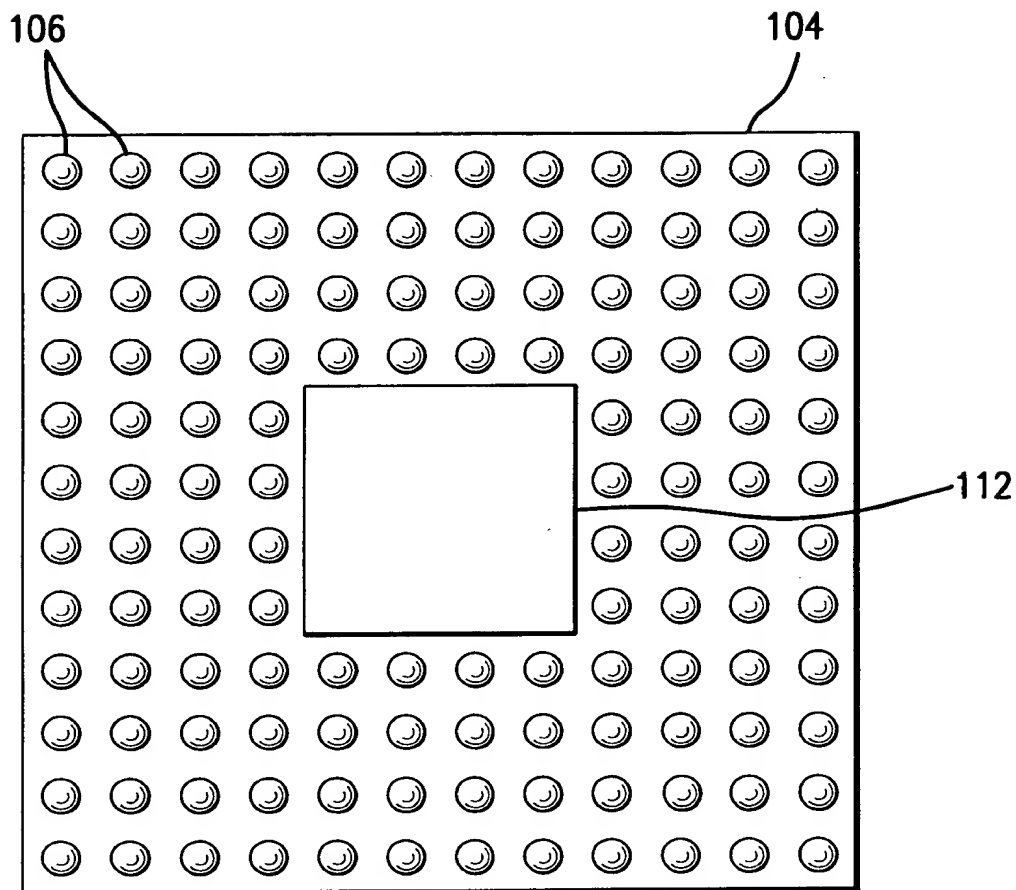


FIG. 4

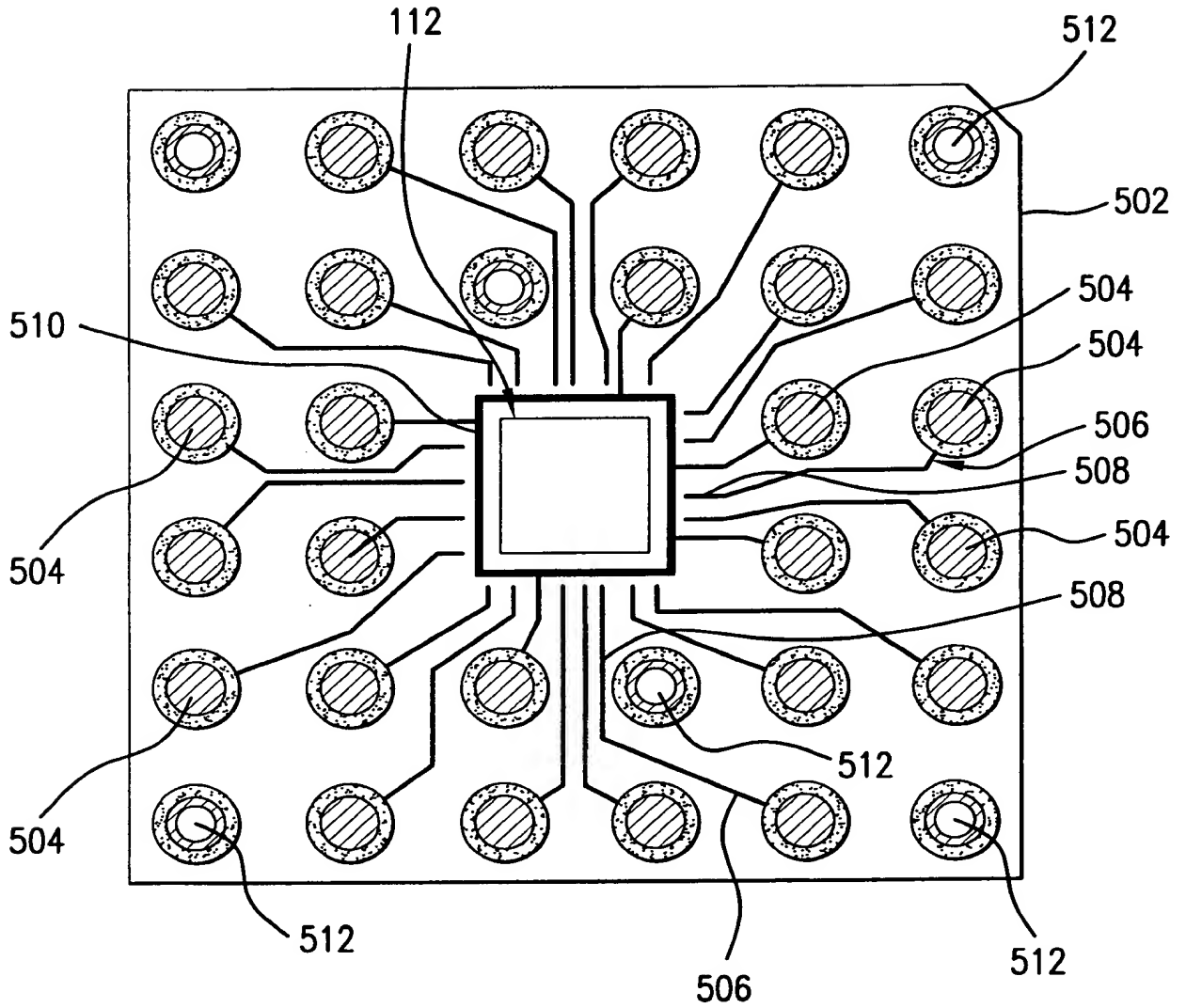


FIG. 5

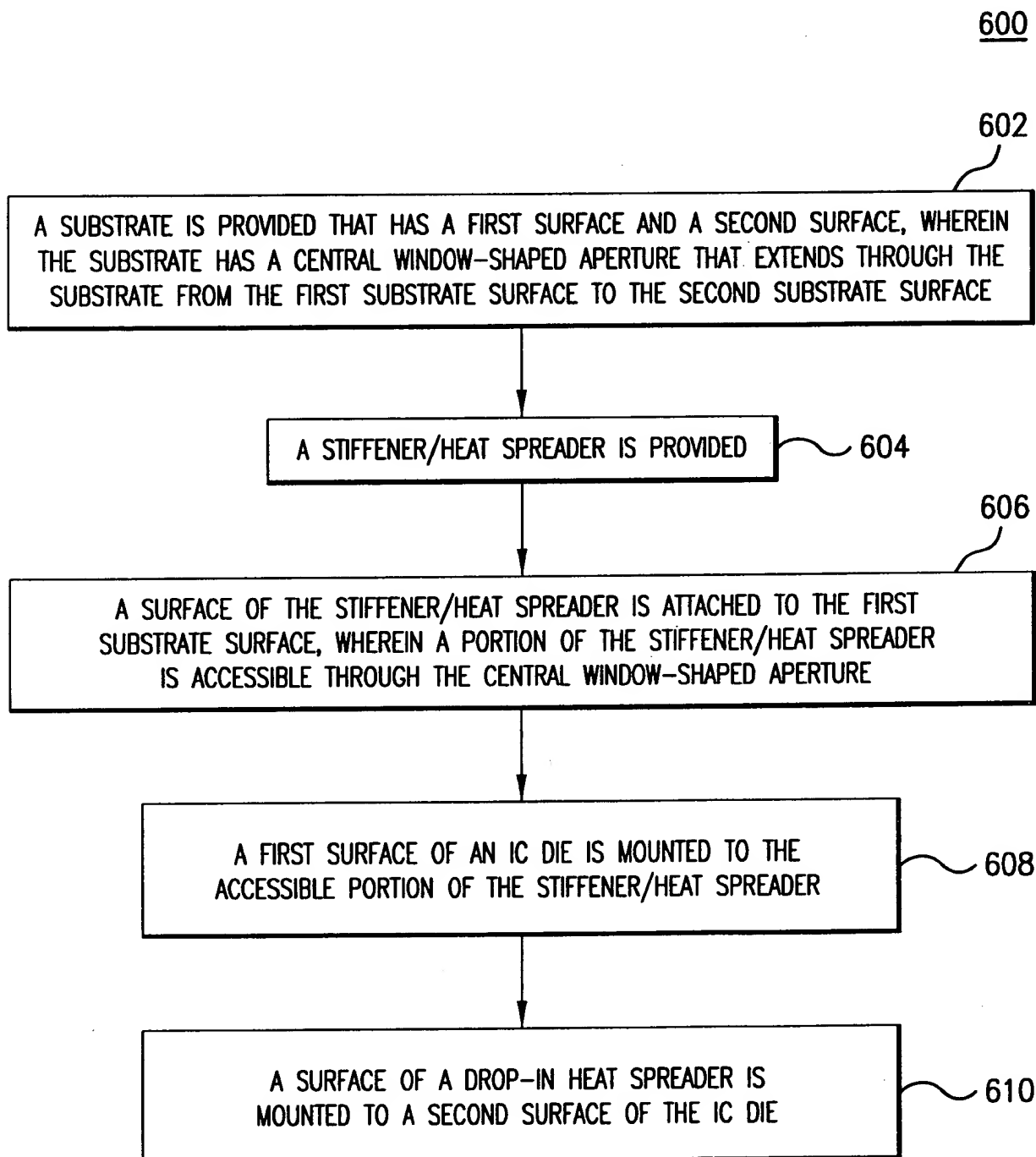


FIG. 6